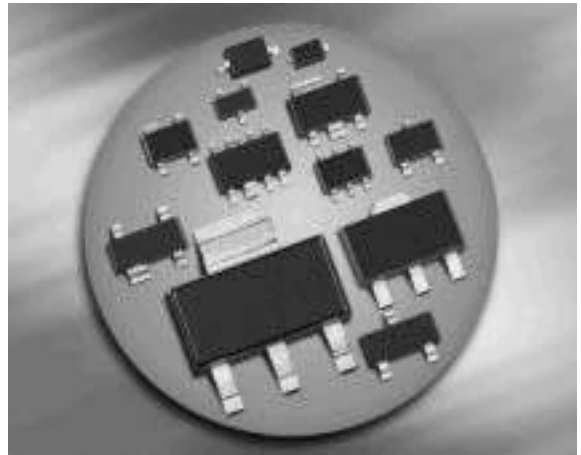
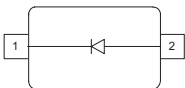


**Medium Power AF Schottky Diode**

- Forward current: 1 A
- Reverse voltage: 30 V
- Very low forward voltage  
(typ. 0.41V @  $I_F = 1A$ )
- For high efficiency DC/DC conversion,  
fast switching, protection and  
clamping applications
- Pb-free (RoHS compliant) package<sup>1)</sup>
- Qualified according AEC Q101


**BAS 3010A-03W**


| Type         | Package | Configuration | Marking |
|--------------|---------|---------------|---------|
| BAS3010A-03W | SOD323  | single        | 4/ blue |

**Maximum Ratings** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

| Parameter   | Symbol    | Value       | Unit             |
|---|-----------|-------------|------------------|
| Diode reverse voltage <sup>2)</sup>   | $V_R$     | 30          | V                |
| Forward current <sup>2)</sup>   | $I_F$     | 1           | A                |
| Average rectified forward current (50/60Hz, sinus)                            | $I_{FAV}$ | 1           |                  |
| Repetitive peak forward current<br>( $t_p \leq 1 \text{ ms}$ , $D \leq 0.5$ ) | $I_{FRM}$ | 3.5         |                  |
| Non-repetitive peak surge forward current<br>( $t \leq 10\text{ms}$ )         | $I_{FSM}$ | 10          |                  |
| Junction temperature  | $T_j$     | 150         | $^\circ\text{C}$ |
| Operating temperature range   | $T_{op}$  | -65 ... 125 |                  |
| Storage temperature   | $T_{stg}$ | -65 ... 150 |                  |

<sup>1)</sup>Pb-containing package may be available upon special request

<sup>2)</sup>For  $T_A > 25^\circ\text{C}$  the derating of  $V_R$  and  $I_F$  has to be considered. Please refer to the attached curves.

**Thermal Resistance**

| Parameter                                | Symbol     | Value     | Unit |
|--|------------|-----------|------|
| Junction - soldering point <sup>1)</sup> | $R_{thJS}$ | $\leq 82$ | K/W  |

**Electrical Characteristics at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

| Parameter | Symbol | Values |      |      | Unit |
|-----------|--------|--------|------|------|------|
|           |        | min.   | typ. | max. |      |

**DC Characteristics**

|                               |       |   |     |     |               |
|-------------------------------|-------|---|-----|-----|---------------|
| Reverse current <sup>2)</sup> | $I_R$ |   |     |     | $\mu\text{A}$ |
| $V_R = 5\text{ V}$            |       | - | 5   | 25  |               |
| $V_R = 10\text{ V}$           |       | - | 10  | 50  |               |
| $V_R = 30\text{ V}$           |       | - | 40  | 200 |               |
| Forward voltage <sup>2)</sup> | $V_F$ |   |     |     | $\text{mV}$   |
| $I_F = 1\text{ mA}$           |       | - | 170 | 220 |               |
| $I_F = 10\text{ mA}$          |       | - | 220 | 270 |               |
| $I_F = 100\text{ mA}$         |       | - | 290 | 340 |               |
| $I_F = 500\text{ mA}$         |       | - | 350 | 410 |               |
| $I_F = 1\text{ A}$            |       | - | 410 | 470 |               |

**AC Characteristics**

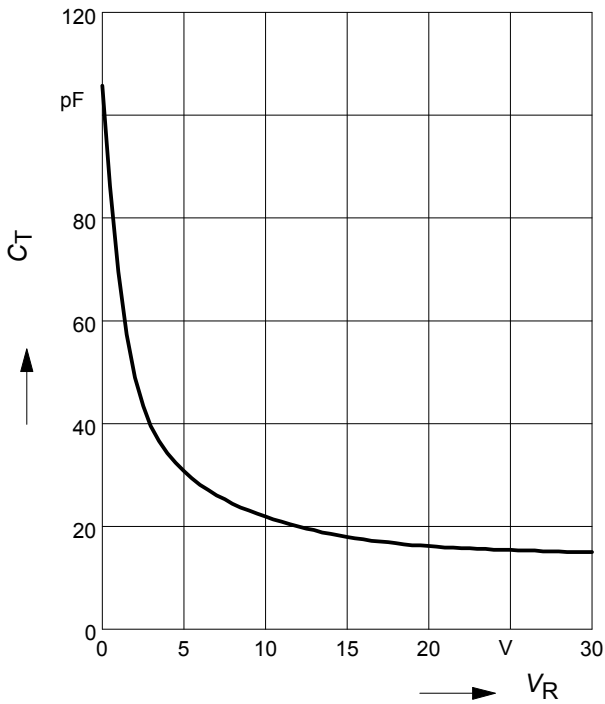
|                                      |       |   |    |    |             |
|--------------------------------------|-------|---|----|----|-------------|
| Diode capacitance                    | $C_T$ | - | 28 | 35 | $\text{pF}$ |
| $V_R = 5\text{ V}, f = 1\text{ MHz}$ |       |   |    |    |             |

<sup>1)</sup>For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

<sup>2)</sup>Pulsed test:  $t_p = 300\ \mu\text{s}$ ;  $D = 0.01$

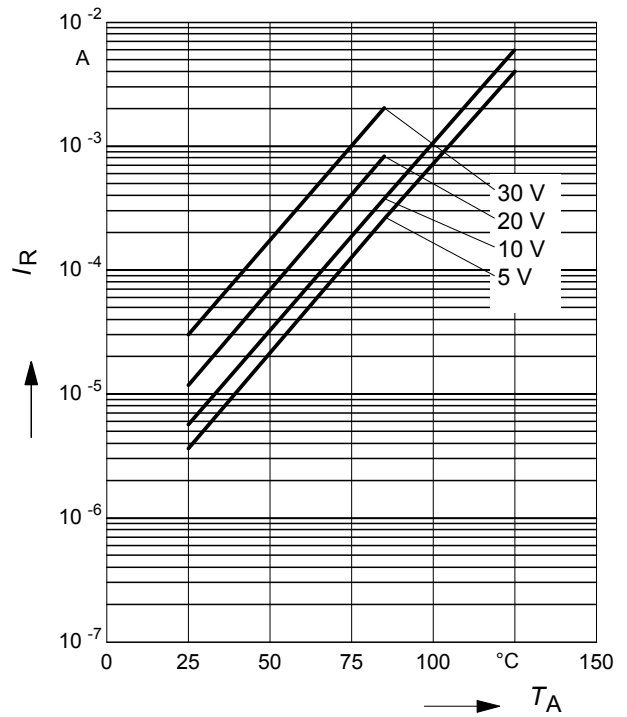
**Diode capacitance  $C_T = f(V_R)$**

$f = 1\text{MHz}$



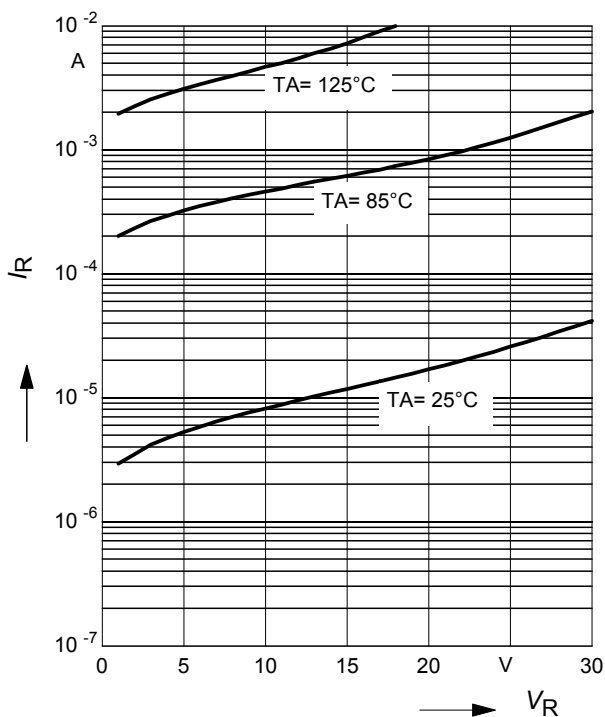
**Reverse current  $I_R = f(T_A)$**

$V_R = \text{Parameter}$



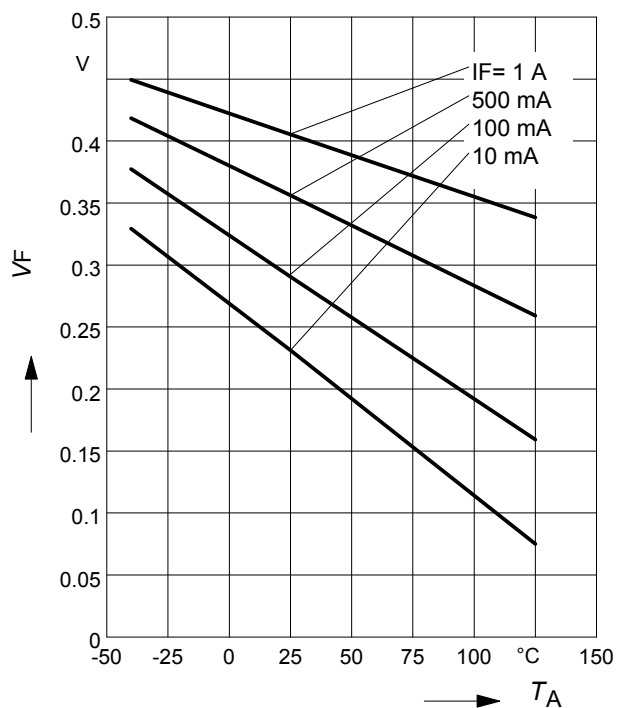
**Reverse current  $I_R = f(V_R)$**

$T_A = \text{Parameter}$



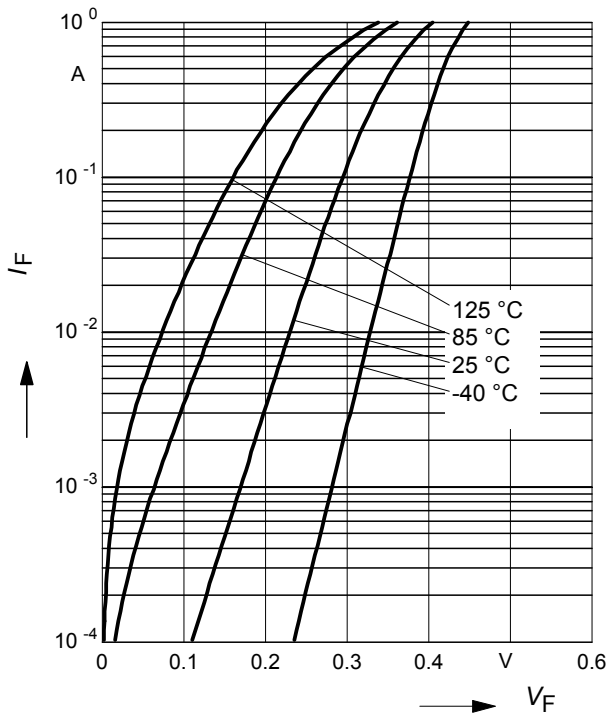
**Forward Voltage  $V_F = f(T_A)$**

$I_F = \text{Parameter}$



**Forward current  $I_F = f(V_F)$**

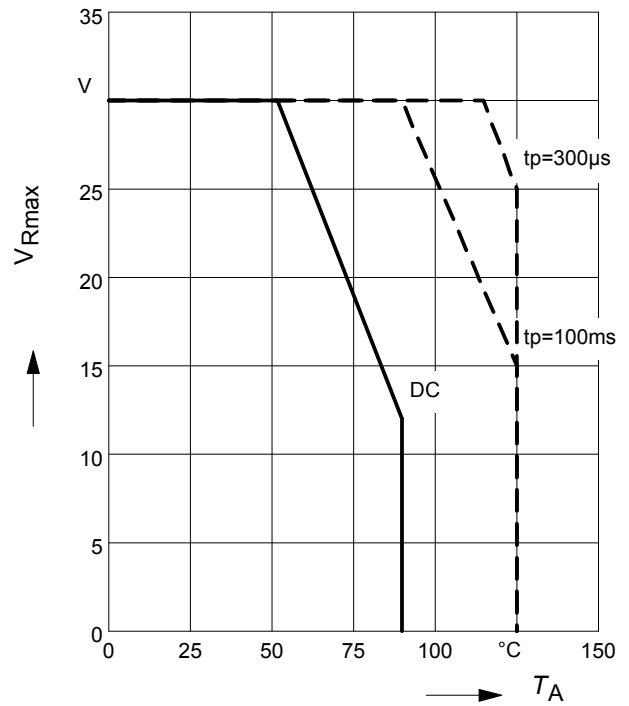
$T_A$  = Parameter



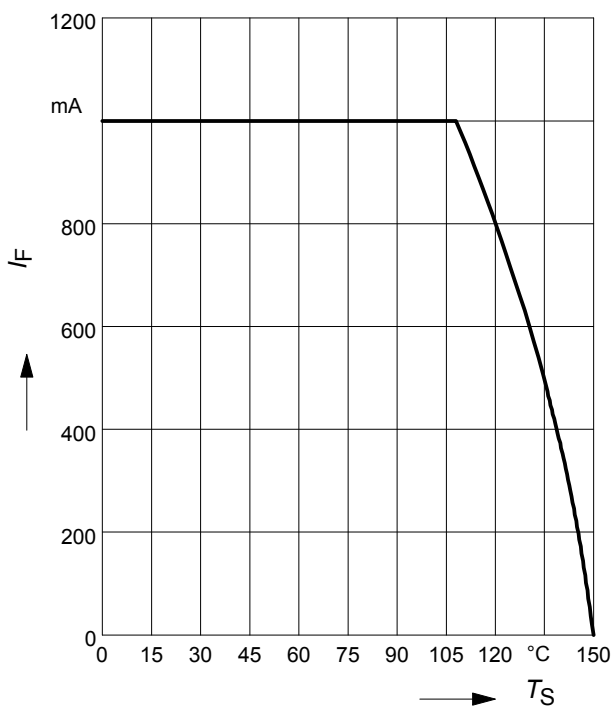
**Permissible Reverse voltage  $V_R = f(T_A)$**

$t_p$  = Parameter, Duty cycle < 0.01

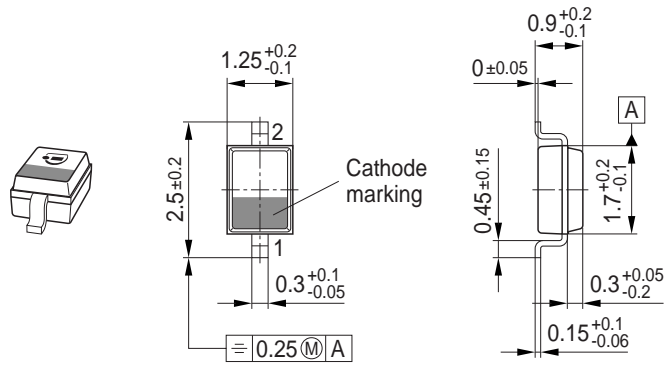
Device mounted on PCB with  $R_{th} = 160$  k/W



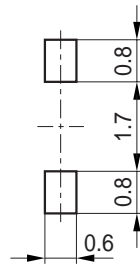
**Forward current  $I_F = f(T_S)$**



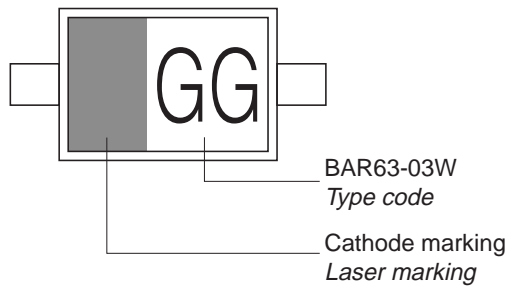
Package Outline



Foot Print

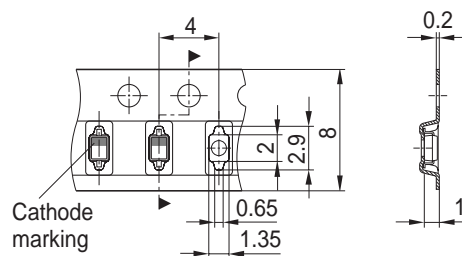


Marking Layout (Example)



Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



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